CLAIMS

1. A pattern formation substrate on which a predetermined pattern is formed by ejecting a droplet to a targeted surface, said pattern formation substrate being characterized by comprising:

a first region where a contact angle at which the droplet contacts the targeted surface is a first contact angle, said first region being formed on the targeted surface; and

one or more second regions where the contact angle of the droplet is a second contact angle smaller than the first contact angle, said second region being formed on the targeted surface so as to be positioned adjacent to the first region, wherein

a surface of the second region is treated so that the droplet moves in a predetermined direction when the droplet is landed.

2. The pattern formation substrate as set forth in claim 1, wherein:

a first line width L_1 and a second line width L_2 are so adjusted as to satisfy an equation (1) below,

$$L_1 > D / \{1 + 2 (\cos\theta_2 - \cos\theta_1)\}$$
 and
$$L_2 > D / \{1 + 2 (\cos\theta_2 - \cos\theta_1)\}.....(1),$$

where:

the first line width L_1 is a width on a side, in the second region, toward which the droplet moves upon landing,

the second line width L_2 is a width on a side, in the second region, opposite to the side toward which the droplet moves,

 θ_1 is the first contact angle of the droplet in the first region,

 θ_2 is the second contact angle of the droplet in the second region, and

D is a diameter of the droplet.

3. The pattern formation substrate as set forth in claim 1, wherein:

each of the contact angles is so adjusted as to satisfy an equation (2) below,

$$L \times \{1 + 2 (\cos \theta_3 - \cos \theta_1)\} < D < L \times \{1 + 2 (\cos \theta_2 - \cos \theta_1)\}$$
...... (2),

where:

 θ_1 is the first contact angle of the first region with respect to the droplet,

 θ_2 is the second contact angle of the second region with respect to one side of the droplet landed,

 θ_3 is a third contact angle of the second region with

respect to another side of the droplet,

- a line width L is a width of the second region, and
- D is a diameter of the droplet; and
- a position of the droplet being landed is targeted so as to overlap the first region and two of the second regions.
- 4. A method for forming a pattern, characterized by comprising the step of forming a predetermined pattern by ejecting a droplet to the pattern formation substrate as set forth in any one of claims 1 through 3.
- 5. The method as set forth in claim 4, wherein a continuous pattern is formed by connecting a plurality of droplets adhering to a targeted surface in a scattering-manner.
- 6. The method as set forth in claim 4, wherein an inkjet head is used for ejecting the droplet.
- 7. The method as set forth in claim 4, wherein the first and the second regions are formed substantially in a flat shape.
- 8. The method as set forth in claim 4, wherein the droplet contains an electrically conductive particle.